NEWS BULLETIN

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For immediate release

NEXX Systems
Installs Nimbus Tool at Unitive in NC
and Ships First 300 mm Tool to Taiwan

Wilmington, MA – February 26, 2003 – NEXX Systems today announced the acceptance of a Nimbus 300 sputter deposition system at the Unitive Electronics, Inc. plant in Research Triangle Park, NC. The Nimbus was selected after an extensive evaluation and is the lowest cost-of-ownership sputtering system on the market for deposition of the under bump metallurgy (UBM) used in Unitive's flip chip process. Flip chip assemblies enable extremely compact, high performance electronic systems, which are in increasing demand for portable electronic devices.

"Using the Nimbus from NEXX Systems gives us a clear cost/performance advantage and provides superior process results," explained Robert Morris, vice president of operations at Unitive. "The NEXX Systems' team were instrumental in satisfying our process requirements and getting the system into production on an tight schedule."

In addition, NEXX Systems announced the shipment of its first 300 mm Nimbus tool, the Model 364, to Unitive Semiconductor Taiwan, where the system will take its place in the first complete 300 mm line for wafer bumping and wafer-level packaging using electroplated solder. NEXX Systems worked in cooperation with its partners in SECAP ("Semiconductor Equipment Consortium for Advanced Packaging") in the installation of their latest 300 mm equipment.

"We are very pleased to participate in creating the leading world class 300 mm electroplated bumping line in our facility," stated Daniel Teng, president of Unitive Taiwan. "We will emphasize our focus on volume manufacturing to rapidly bring viable solutions to the marketplace in response to our customers' demand."

"We are very pleased to have won Unitive's business. The acceptance and shipment of these systems represent key milestones in our young company history," said Michael Gustafson, Director of Sales and Service at NEXX Systems. "We recognize Unitive as a leader in advanced packaging and believe this installation is the beginning of a very fruitful relationship for both companies."

Unitive is a leading provider of wafer-level packaging solutions that make semiconductors smaller, faster, and lighter. The company partners with its customers to meet their product and global manufacturing needs through innovative deployment of its technologies. Unitive's services include multi-level passivation and thin film wiring, solder bumping, and chip scale packaging.

NEXX Systems designs, develops, and manufactures technologically advanced solutions for the semiconductor advanced packaging, telecommunications, and optoelectronics markets. NEXX

Systems' products provide established platforms specifically focused on flip chip advanced packaging, including wafer metallization, wafer cleaning, photoresist strip, and related technologies. Additional information can be found at: *www.nexxsystems.com*.

Additional information on SECAP can be found at: *www.secap.org*.

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